

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	320	glass near (substrate or board) and (vias or (through near holes)) and filler	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:14
S2	30	glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:15
S3	49	361/760 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:55
S7	13	361/750 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:55
S8	11	361/751 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:55
S9	18	361/761 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:55
S10	7	361/765 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:56
S11	14	361/767 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:56
S12	6	361/768 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:56

S13	11	361/772 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:56
S29	26	levi near dameon	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/03/07 17:00
S30	1	gandhi near jay	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/03/07 17:00
S38	52	361/760 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:56
S39	26	361/748 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S40	15	361/750 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S41	13	361/751 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S42	16	361/761 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S43	8	361/765 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S44	19	361/767 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57

S45	7	361/768 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S46	10	361/772 and glass near (substrate or board) and (vias or (through near holes))	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2003/08/20 15:57
S57	284	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:15
S58	53	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and (display adj1 device)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:17
S59	10	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and (display adj1 device)and((conduct\$ or wiring) adj1 pattern)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:47
S60	69	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and((conduct\$ or wiring) adj1 pattern)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:22
S61	414	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and ((conduct\$ or wiring) adj1 pattern)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:48
S62	29	"361"/\$.ccls.and (glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and ((conduct\$ or wiring) adj1 pattern)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2004/12/20 16:48